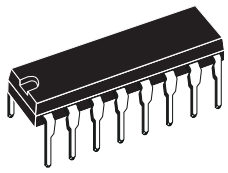
L6210

Dual Schottky diode bridge

Features

- Monolithic array of eight Schottky diodes
- High efficiency
- 4 A peak current
- Low forward voltage
- Fast recovery
- Time two separated diode bridges



PDIP 16

The L6210 is available in a 16 pin powerdip package (12 + 2 + 2) designed for the 0 to 70°C ambient temperature range.

Description

The L6210 is a monolithic IC containing eight Schottky diodes arranged as two separated diode bridges.

This diodes connection makes this device versatile in many applications.

They are used particular in bipolar stepper motor applications, where high efficient operation, due to low forward voltage drop and fast reverse recovery time, are required.

Table 1. Device summary

Order code	Package	Packing
E-L6210	PDIP 16	Tube

Contents

1 Block and pin connection diagram 3

2 Electrical specifications 4

2.1 Absolute maximum ratings 4

2.2 Thermal data 4

2.3 Electrical characteristics 4

3 Mounting instructions 5

4 Package information 6

5 Revision history 7

1 Block and pin connection diagram

Figure 1. Block diagram

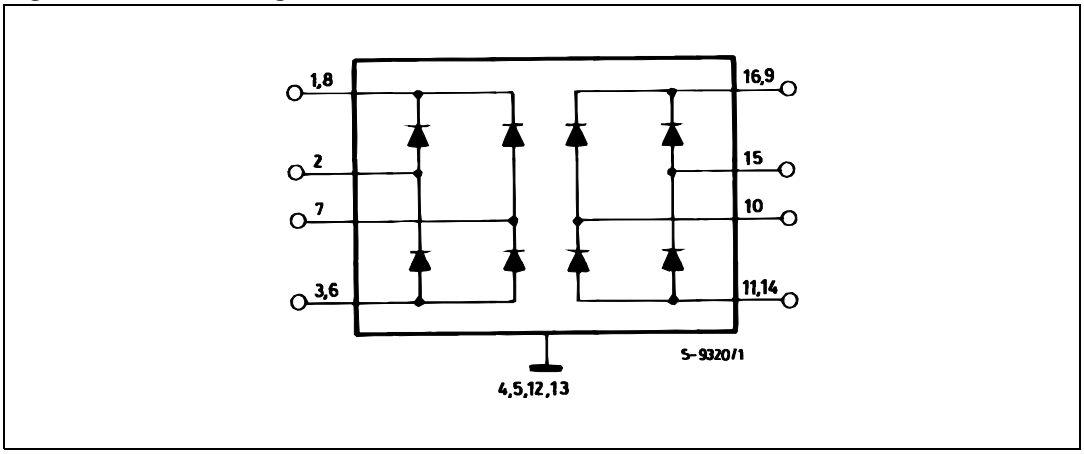
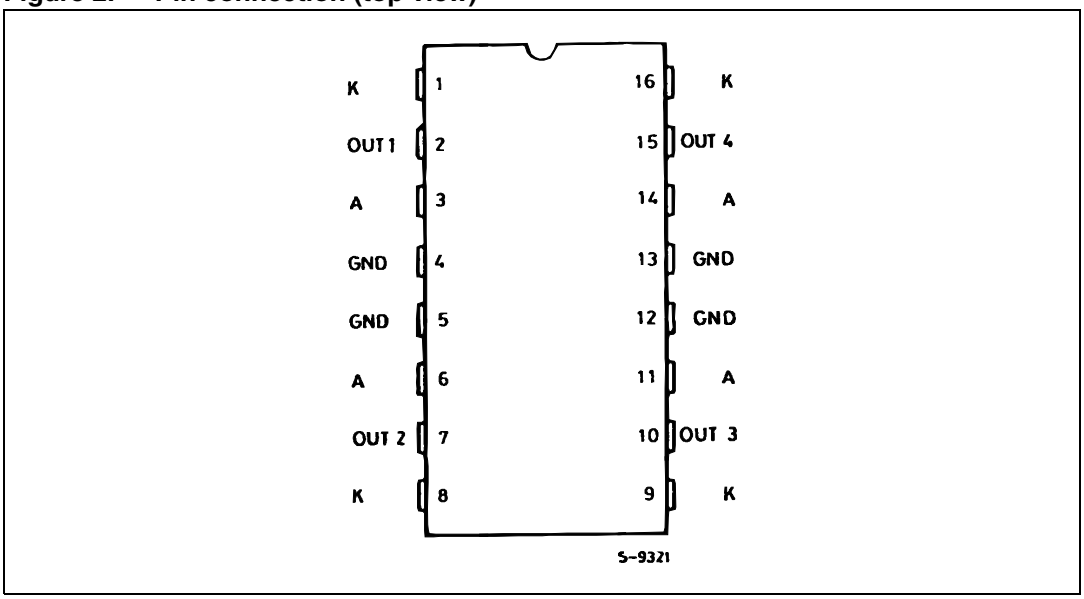


Figure 2. Pin connection (top view)



2 Electrical specifications

2.1 Absolute maximum ratings

Table 2. Absolute maximum ratings

Symbol	Parameter	Value	Unit
I_F	Repetitive Forward Current Peak	2	A
V_R	Peak Reverse Voltage (per diode)	50	V
T_{AMB}	Operating Ambient Temperature	70	°C
T_{STG}	Storage Temperature Range	–55 to +150	°C

2.2 Thermal data

Table 3. Thermal data

Symbol	Parameter	Min.	Typ.	Max.	Unit
$R_{TH\ J\text{-}CASE}$	Thermal Impedance Junction-case			14	°C/W
$R_{TH\ J\text{-}AMB}$	Thermal Impedance Junction-ambient without External Heatsink			65	°C/W

2.3 Electrical characteristics

Table 4. Electrical characteristics
(T_J = 25°C unless otherwise specified)

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
V_F	Forward Voltage Drop	I_F = 100 mA		0.65	0.8	V
		I_F = 500 mA		0.8	1	V
		I_F = 1 A		1	1.2	V
I_L	Leakage Current	V_R = 40 V, T_{AMB} = 25 °C			1	mA

Note: At forward currents of greater than 1 A, a parasitic current of approximately 10 mA may be collected by adiacent diodes.

3 Mounting instructions

The $R_{th\ j\text{-}amb}$ of the L6210 can be reduced by soldering the GND pins to suitable copper area of the printed circuit boards as shown in *Figure 3* or to an external heatsink (*Figure 4*). During soldering the pin temperature must not exceed 260°C and the soldering time must not be longer then 12 s. The external heatsink or printed circuit copper area must be connected to electrical ground.

Figure 3. Example of PC board copper area which is used as heatsink

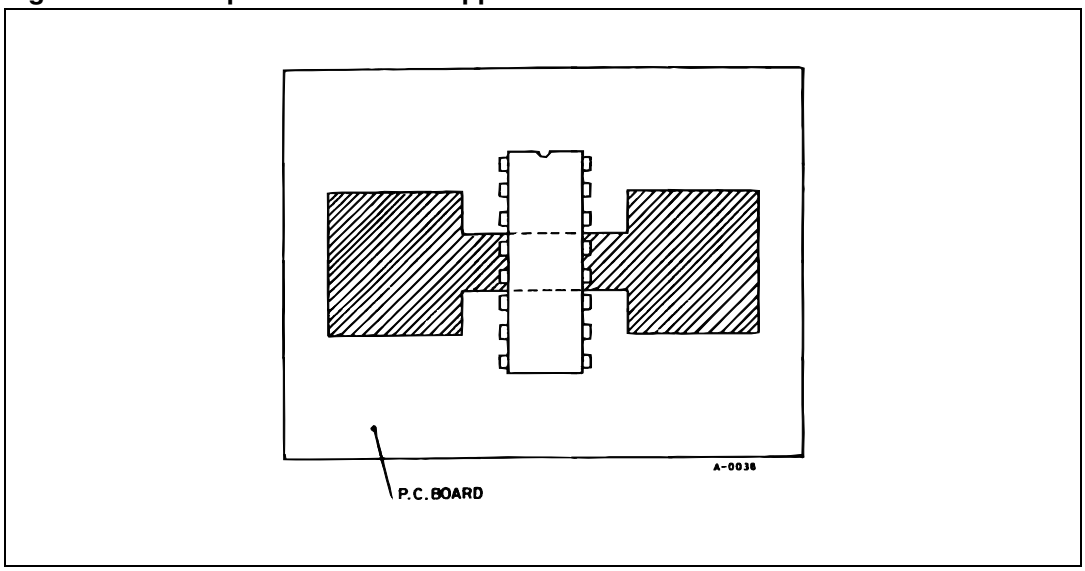
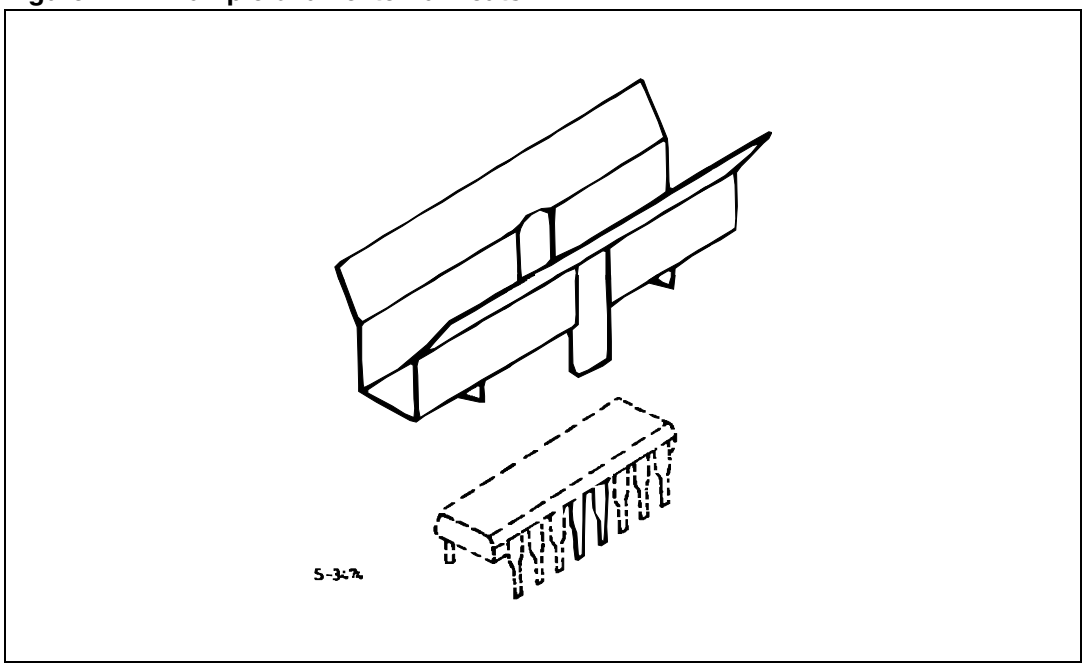


Figure 4. Example of an external heatsink



4 Package information

In order to meet environmental requirements, ST (also) offers these devices in ECOPACK® packages. ECOPACK® packages are lead-free. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label.

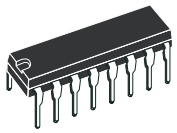
ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

Figure 5. PDIP 16 mechanical data and package dimensions

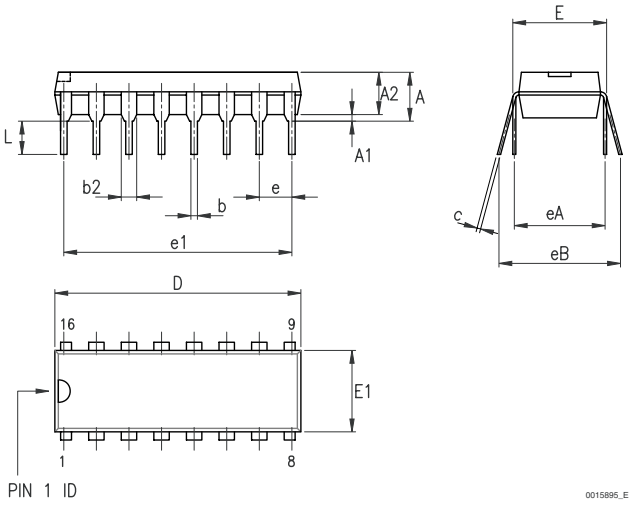
DIM.	mm			inch		
	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.
A			5.330			0.2098
A1	0.380			0.0150		
A2	2.920	3.300	4.950	0.1150	0.1299	0.1949
b	0.360	0.460	0.560	0.0142	0.0181	0.0220
b2	1.140	1.520	1.780	0.0449	0.0598	0.0701
c	0.200	0.250	0.360	0.0079	0.0098	0.0142
D(*)	18.670	19.180	19.690	0.7350	0.7551	0.7752
E	7.620	7.870	8.260	0.3000	0.3098	0.3252
E1(*)	6.100	6.350	7.110	0.2402	0.2500	0.2799
e		2.540			0.1000	
e1		17.780			0.7000	
eA		7.620			0.3000	
eB			10.920			0.4299
L	2.920	3.300	3.810	0.1150	0.1299	0.1500

(*)"D" and "E1" dimensions do not include mold flash or protusions. Mold flash or protusions shall not exceed 0.25mm.

OUTLINE AND MECHANICAL DATA



PDIP 16



0015895 E

5 Revision history

Table 5. Document revision history

Date	Revision	Changes
31-Jul-2003	1	Initial release.
23-Apr-2008	2	Package information updated.

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